

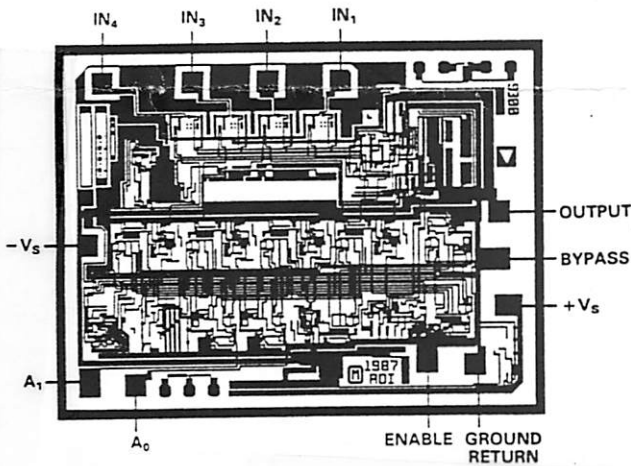


# Sierra Components, Inc.

924 Incline Way • Suite F • Incline Village, Nevada 89451  
 Phone: 775.831.1241 Fax: 775.831.3021

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

METALIZATION PHOTOGRAPH



### MECHANICAL INFORMATION

Die Dimensions . . . . . 84 × 104 × 18 (max) mils  
 Pad Dimensions . . . . . 4 × 4 (min) mils  
 Metalization . . . . . Aluminum  
 Backing . . . . . None  
 Substrate Potential . . . . . -Vs  
 Passivation . . . . . Oxynitride  
 Die Attach . . . . . Gold Eutectic  
 Bond Wire . . . . . 1.25 mil, Aluminum; Ultrasonic Bonding  
 or 1 mil, Gold; Gold Ball Bonding

**Topside Metal: Al (Aluminum)**

**Backside:**

**Backside Potential:**

**Mask Ref:**

**Bond Pads (Mils): 4 X 4**

**APPROVED BY:**  
**MFG: Analog Devices**

**DIE SIZE (Mils): 84 X 104**  
**THICKNESS: 18**

**DATE: 3/2/00**  
**P/N: AD9300**

DG 10.1.2  
 Rev A 3-4-99